



IPC-610HC

Telecom Addendum to IPC-A-610 Revision H Acceptability of Electronic Assemblies

Developed by the IPC-A-610 Telecom Addendum Task Group (7-31bc)
of the Product Assurance Subcommittee (7-30) of IPC

Users of this publication are encouraged to participate in the
development of future revisions.

Contact:

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IPC
3000 Lakeside Drive, Suite 105N
Bannockburn, Illinois
60015-1249
Tel 847 615.7100
Fax 847 615.7105

Acknowledgment

Any document involving a complex technology draws material from a vast number of sources across many continents. While the principal members of the IPC-A-610 Telecom Addendum Task Group comprised of IPC Task Group (7-31bc) of the Product Assurance Subcommittee (7-30) are shown below, it is not possible to include all of those who assisted in the evolution of this standard. To each of them, the members of IPC extend their gratitude.

Product Assurance Committee

Chair

Robert Cooke
NASA Johnson Space Center

Vice Chair

Debbie Wade
Advanced Rework Technology

IPC-A-610 Working Group

Chair

Darrin Dodson
Nokia

Technical Liaison of the IPC Board of Directors

Bob Neves
Microtek (Changzhou)
Laboratories

Members of 7-31BC IPC-A-610 Telecom Addendum Task Group

Debbie Wade, Advanced Rework
Technology

Agnieszka Ozarowski, BAE Systems

Sean Keating, Clonfert Solutions Ltd

Andrew Giamis, Commscope

Miguel Dominguez, Continental
Automotive

Symon Franklin, Custom
Interconnect Ltd

Vasu Vasudevan, Dell Inc.

Adam Fidura, Dyson Technology
Limited

Constantin Hudon, East West Quebec

Francesco Di Maio, GESTLABS S.r.l.

Claus Molgaard, GN Hearing A/S

Lalith Bandara, GPV Lanka (Pvt) Ltd.

Beverley Christian, HDP User Group

David Hillman, Hillman Electronic
Assembly Solutions LLC

Jennie Hwang, H-Technologies Group

Mingye Wang, Junfeng Electronics
Control Technology Dalian Co., Ltd.

Latha M.S, Kaynes Technology India
Pvt. Ltd

Vijay Kumar, Lockheed Martin
Missiles & Fire Control

Trevor Bowers, Lockheed Martin
Space Systems Co.

Rex Chang, Molex Taiwan Ltd.
Sanchong Branch

Edward Rios, Motorola Solutions

Robert Cooke, NASA Johnson
Space Center

Darrin Dodson, Nokia

Behdis Nowrouzi, Nokia

Toshiyuki Sugiyama, Omron
Corporation-Inspection Systems
Business Division

Ping Zhao, Shaanxi, Fenghuo
Electronics Co., Ltd

Chengyan Cui, Shenyang Railway
Signal Co., Ltd.

Tom Hamelincx, ST Engineering
iDirect

Robert Fornefeld, STI Electronics, Inc.

Michael Collier, Teledyne Advanced
Electronic Solutions

Stephen Tisdale, Tisdale Environmental
Consulting LLC

Gaston Hidalgo, Toyota Motor North
America

Jose Servin Olivares, Vitesco
Technologies

Zhiman Chen, ZhuZhou CRRC Times
Electric Co., Ltd.

IPC-A-610 Revision H Telecom Addendum

0.1 Scope This Addendum provides requirements to be used in addition to, and in some cases, in place of, those published in IPC-A-610 Revision H to ensure that electrical and electronic assemblies meet requirements for customers requiring Telcordia GR-78-CORE compliance.

Where content criteria are not supplemented, the Class 2 requirements of IPC-A-610 Revision H apply.

This addendum contains criteria for process control.

0.1.1 Purpose When required by procurement documentation/drawings, this Addendum supplements or replaces specifically identified requirements of IPC-A-610 Revision H.

0.1.2 Precedence Customer contractual requirements take precedence over this Addendum, referenced standards and User-approved drawings. In the event of a conflict between this Addendum and the applicable documents cited herein, this Addendum takes precedence. Where referenced criteria of this Addendum differ from the published IPC-A-610 Revision H, this Addendum takes precedence.

0.1.3 Existing or Previously Approved Designs This Addendum **shall not** constitute the sole cause for the redesign of previously approved designs. When drawings for existing or previously approved designs undergo revision they should be reviewed and changes made that allow for compliance with the requirements of this Addendum.

0.1.4 Use This Addendum is applicable for rigid single-sided, double-sided, and multilayer boards. This Addendum **shall not** be used as a standalone document.

Where criteria are not supplemented, the Class 2 requirements of IPC-A-610 Revision H apply. Criteria defined in IPC-A-610 Revision H as "process defects" for Class 2 **shall** be treated as defective, unless otherwise stated in this Addendum.

If an IPC-A-610 Revision H requirement is changed or added by this Addendum, the clause is identified and that entire IPC-A-610 Revision H clause or subordinate clause is replaced by the criteria in this Addendum.

The clauses modified by this Addendum do not include subordinate clauses unless specifically stated, e.g., 1.4 does not include 1.4.1. Clauses, Tables, Figures, etc., in IPC-A-610 Revision H that are not listed in this Addendum are to be used as-published.

In this Addendum, as in the published IPC-A-610 Revision H, in case of conflict or discrepancy, the description or written criteria always take precedence over the illustrations.

The surface insulation resistance and the electromigration resistance of the finished PWB **shall** be in accordance with GR-78-CORE. This is relevant for no-clean assembly processes, which should be used preferably, as well as for fluxes which are intended to be cleaned, and for SMC adhesives.

Solder alloy **shall** comply with J-STD-006 or equivalent.

0.1.5 Additional Referenced Standards Telcordia GR-78-CORE Generic Requirements for the Physical Design and Manufacture of Telecommunications Products and Equipment (<http://telecom-info.telcordia.com>).

1.8.5 Electrical Clearance

These criteria replace all of 1.8.5 Electrical Clearance in published IPC-A-610 Revision H.

Minimum electrical clearance for products built to this document is specified as 0.13 mm [0.005 in].